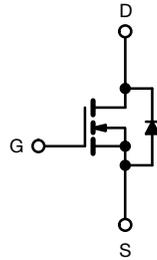
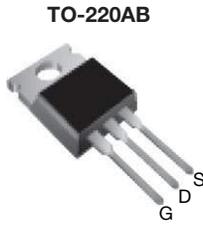


Power MOSFET



N-Channel MOSFET

FEATURES

- Low gate charge Q_g results in simple drive requirement
- Improved gate, avalanche and dynamic dV/dt ruggedness
- Fully characterized capacitance and avalanche voltage and current
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912


 Available
RoHS*
 Available

APPLICATIONS

- Switch mode power supply (SMPS)
- Uninterruptible power supply
- High speed power switching

APPLICABLE OFF LINE SMPS TOPOLOGIES

- Active clamped forward
- Main switch

PRODUCT SUMMARY	
V_{DS} (V)	600
$R_{DS(on)}$ (Ω)	$V_{GS} = 10\text{ V}$ 0.75
Q_g max. (nC)	49
Q_{gs} (nC)	13
Q_{gd} (nC)	20
Configuration	Single

ORDERING INFORMATION	
Package	TO-220AB
Lead (Pb)-free	IRFB9N60APbF
Lead (Pb)-free and halogen-free	IRFB9N60APbF-BE3

ABSOLUTE MAXIMUM RATINGS ($T_C = 25\text{ }^\circ\text{C}$, unless otherwise noted)					
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-source voltage		V_{DS}	600	V	
Gate-source voltage		V_{GS}	± 30		
Continuous drain current	V_{GS} at 10 V	I_D	$T_C = 25\text{ }^\circ\text{C}$	9.2	A
			$T_C = 100\text{ }^\circ\text{C}$	5.8	
Pulsed drain current ^a		I_{DM}	37		
Linear derating factor			1.3	W/ $^\circ\text{C}$	
Single pulse avalanche energy ^b		E_{AS}	290	mJ	
Repetitive avalanche current ^a		I_{AR}	9.2	A	
Repetitive avalanche energy ^a		E_{AR}	17	mJ	
Maximum power dissipation	$T_C = 25\text{ }^\circ\text{C}$	P_D	170	W	
Peak diode recovery dV/dt ^c		dV/dt	5.0	V/ns	
Operating junction and storage temperature range		T_J, T_{stg}	-55 to +150	$^\circ\text{C}$	
Soldering recommendations (peak temperature) ^d	For 10 s		300		
Mounting torque	6-32 or M3 screw		10		lbf · in
			1.1	N · m	

Notes

- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- Starting $T_J = 25\text{ }^\circ\text{C}$, $L = 6.8\text{ mH}$, $R_g = 25\text{ }\Omega$, $I_{AS} = 9.2\text{ A}$ (see fig. 12)
- $I_{SD} \leq 9.2\text{ A}$, $dI/dt \leq 50\text{ A}/\mu\text{s}$, $V_{DD} \leq V_{DS}$, $T_J \leq 150\text{ }^\circ\text{C}$
- 1.6 mm from case



THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum junction-to-ambient	R_{thJA}	-	62	°C/W
Case-to-sink, flat, greased surface	R_{thCS}	0.50	-	
Maximum junction-to-case (drain)	R_{thJC}	-	0.75	

SPECIFICATIONS ($T_J = 25\text{ }^\circ\text{C}$, unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-source breakdown voltage	V_{DS}	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$		600	-	-	V
V_{DS} temperature coefficient	$\Delta V_{DS}/T_J$	Reference to $25\text{ }^\circ\text{C}$, $I_D = 1\text{ mA}$		-	660	-	mV/°C
Gate-source threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$		2.0	-	4.0	V
Gate-source leakage	I_{GSS}	$V_{GS} = \pm 30\text{ V}$		-	-	± 100	nA
Zero gate voltage drain current	I_{DSS}	$V_{DS} = 600\text{ V}, V_{GS} = 0\text{ V}$		-	-	25	μA
		$V_{DS} = 480\text{ V}, V_{GS} = 0\text{ V}, T_J = 125\text{ }^\circ\text{C}$		-	-	250	
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS} = 10\text{ V}$	$I_D = 5.5\text{ A}^b$	-	-	0.75	Ω
Forward transconductance	g_{fs}	$V_{DS} = 50\text{ V}, I_D = 5.5\text{ A}$		5.5	-	-	S
Dynamic							
Input capacitance	C_{iss}	$V_{GS} = 0\text{ V}, V_{DS} = 25\text{ V}, f = 1.0\text{ MHz}$, see fig. 5		-	1400	-	pF
Output capacitance	C_{oss}			-	180	-	
Reverse transfer capacitance	C_{rss}			-	7.1	-	
Output capacitance	C_{oss}	$V_{GS} = 0\text{ V}$	$V_{DS} = 1.0\text{ V}, f = 1.0\text{ MHz}$	-	1957	-	pF
			$V_{DS} = 480\text{ V}, f = 1.0\text{ MHz}$	-	49	-	
Effective output capacitance	$C_{oss\text{ eff.}}$	$V_{DS} = 0\text{ V to } 480\text{ V}$		-	96	-	pF
Total gate charge	Q_g	$V_{GS} = 10\text{ V}$	$I_D = 9.2\text{ A}, V_{DS} = 400\text{ V}$ see fig. 6 and 13 ^b	-	-	49	nC
Gate-source charge	Q_{gs}			-	-	13	
Gate-drain charge	Q_{gd}			-	-	20	
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 300\text{ V}, I_D = 9.2\text{ A}$ $R_g = 9.1\text{ }\Omega, R_D = 35.5\text{ }\Omega$, see fig. 10 ^b		-	13	-	ns
Rise time	t_r			-	25	-	
Turn-off delay time	$t_{d(off)}$			-	30	-	
Fall time	t_f			-	22	-	
Gate input resistance	R_g	$f = 1\text{ MHz}$, open drain		0.5	-	3.2	Ω
Drain-Source Body Diode Characteristics							
Continuous source-drain diode current	I_S	MOSFET symbol showing the integral reverse p-n junction diode 		-	-	9.2	A
Pulsed diode forward current ^a	I_{SM}			-	-	37	
Body diode voltage	V_{SD}	$T_J = 25\text{ }^\circ\text{C}, I_S = 9.2\text{ A}, V_{GS} = 0\text{ V}^b$		-	-	1.5	V
Body diode reverse recovery time	t_{rr}	$T_J = 25\text{ }^\circ\text{C}, I_F = 9.2\text{ A}, dI/dt = 100\text{ A}/\mu\text{s}^b$		-	530	800	ns
Body diode reverse recovery charge	Q_{rr}			-	3.0	4.4	μC
Forward turn-on time	t_{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L_S and L_D)					

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. Pulse width $\leq 300\text{ }\mu\text{s}$; duty cycle $\leq 2\%$
- c. C_{oss} effective is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS}



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

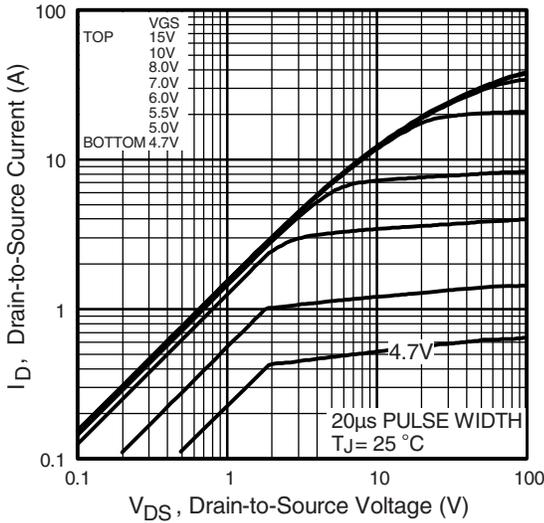


Fig. 1 - Typical Output Characteristics

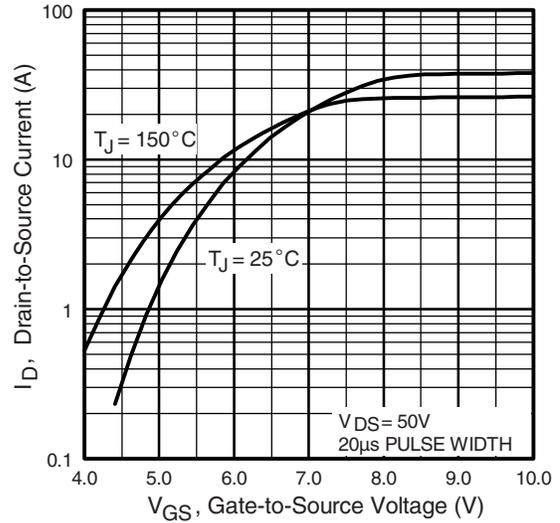


Fig. 3 - Typical Transfer Characteristics

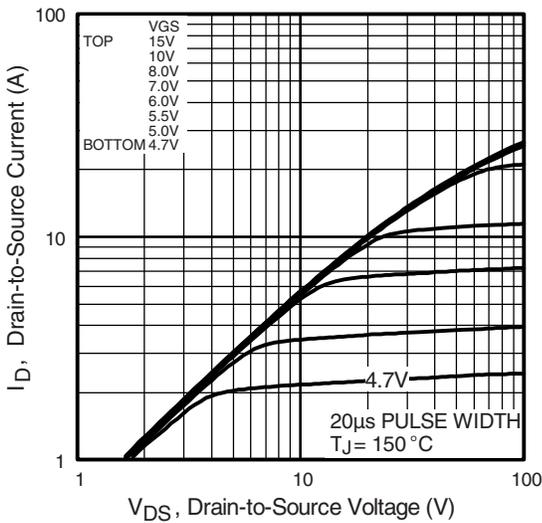


Fig. 2 - Typical Output Characteristics

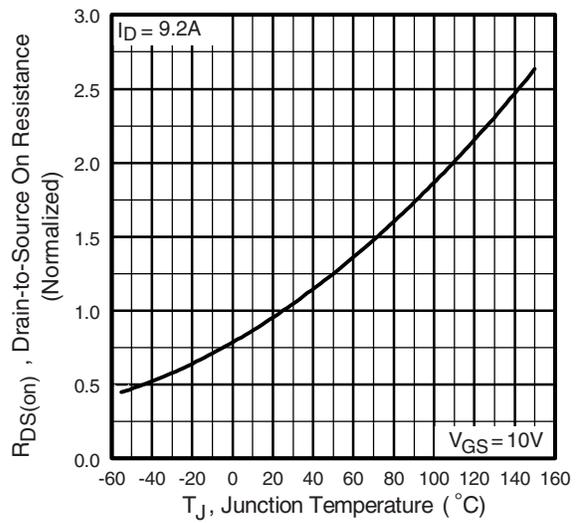


Fig. 4 - Normalized On-Resistance vs. Temperature

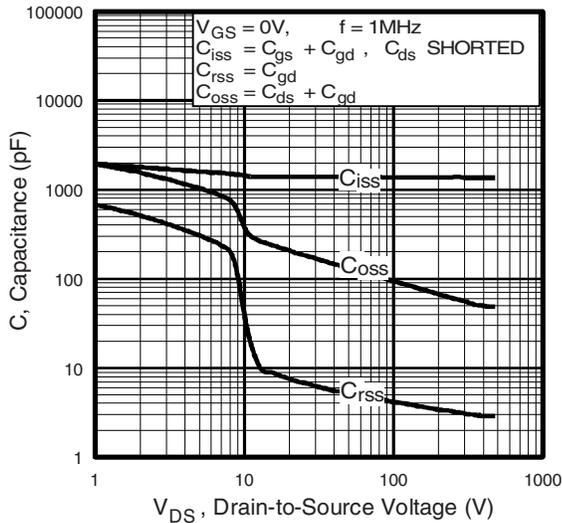


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

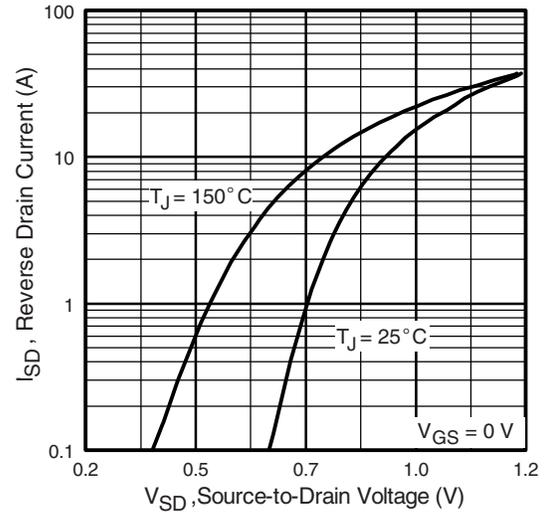


Fig. 7 - Typical Source-Drain Diode Forward Voltage

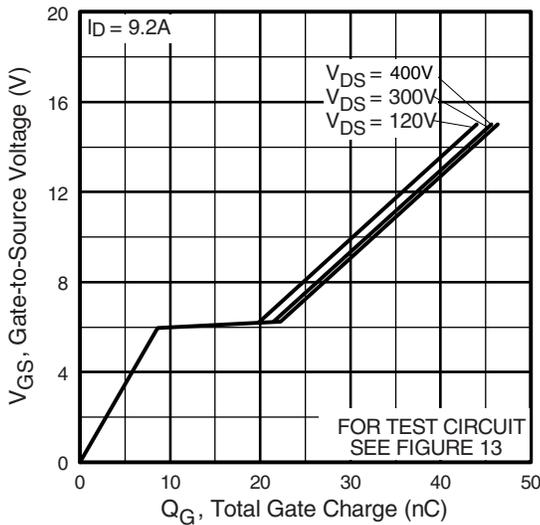


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

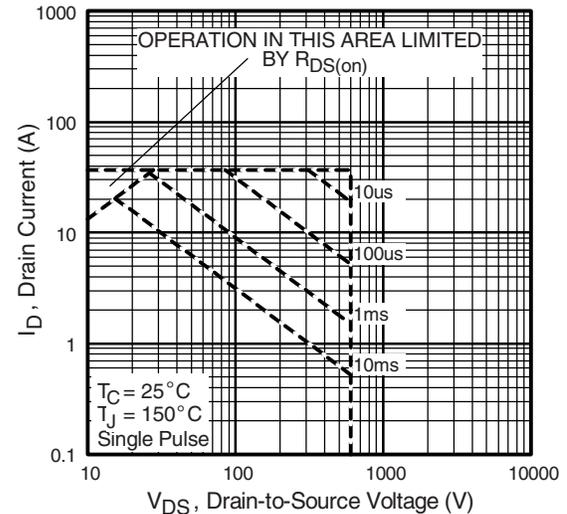


Fig. 8 - Maximum Safe Operating Area

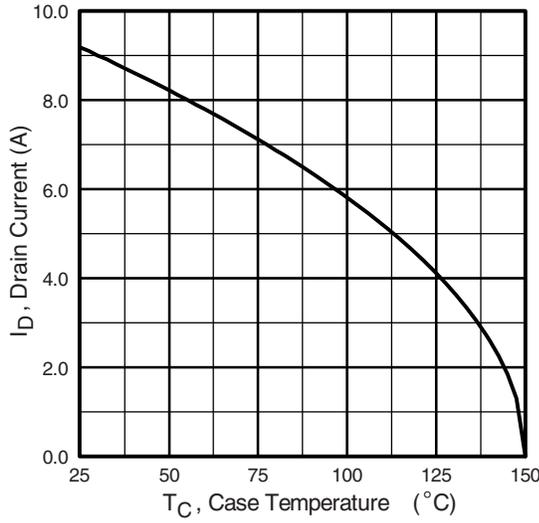


Fig. 9 - Maximum Drain Current vs. Case Temperature

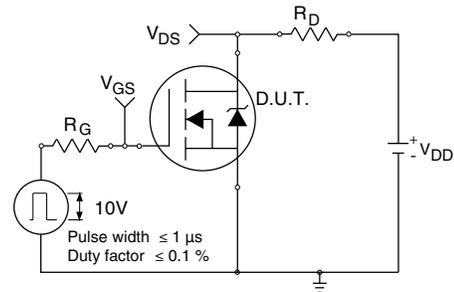


Fig. 10a - Switching Time Test Circuit

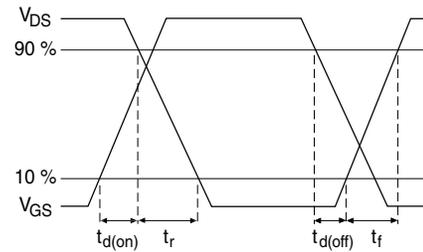


Fig. 10b - Switching Time Waveforms

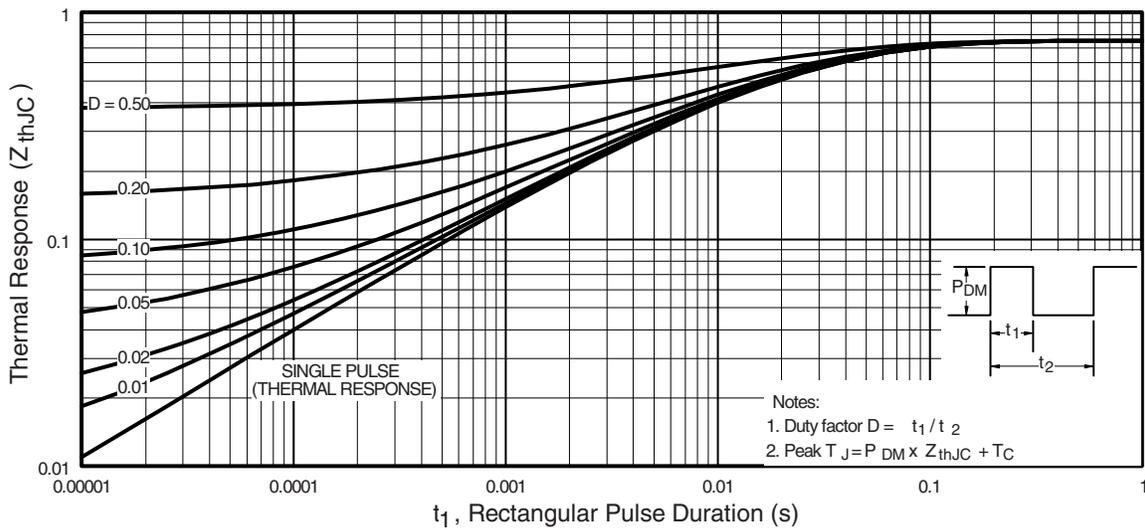


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

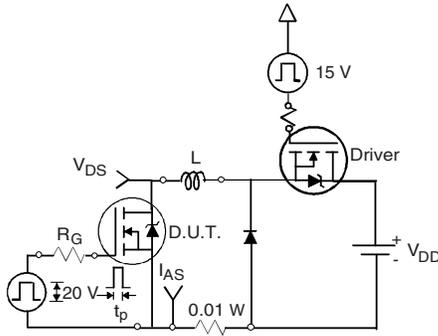


Fig. 12a - Unclamped Inductive Test Circuit

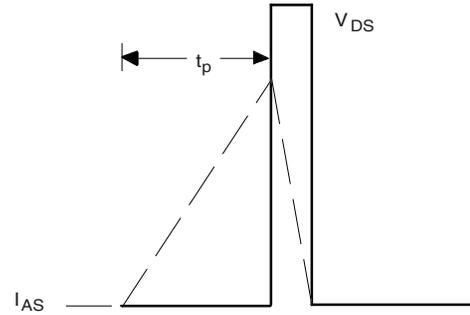


Fig. 12b - Unclamped Inductive Waveforms

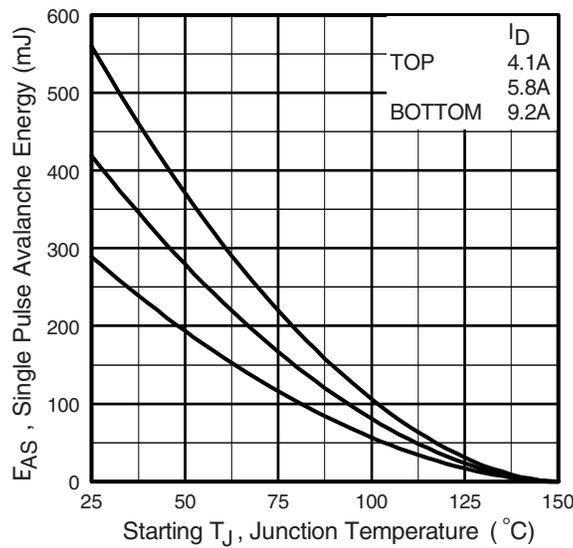


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

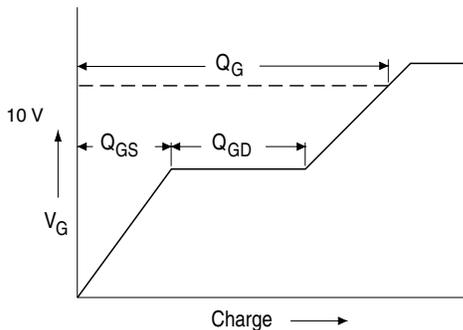


Fig. 13a - Basic Gate Charge Waveform

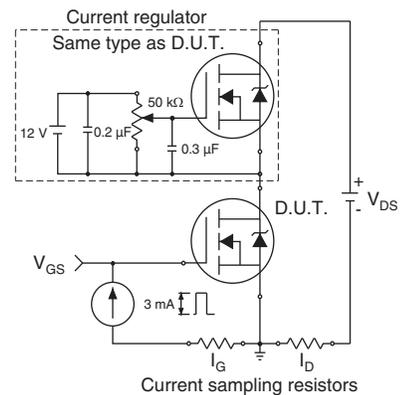
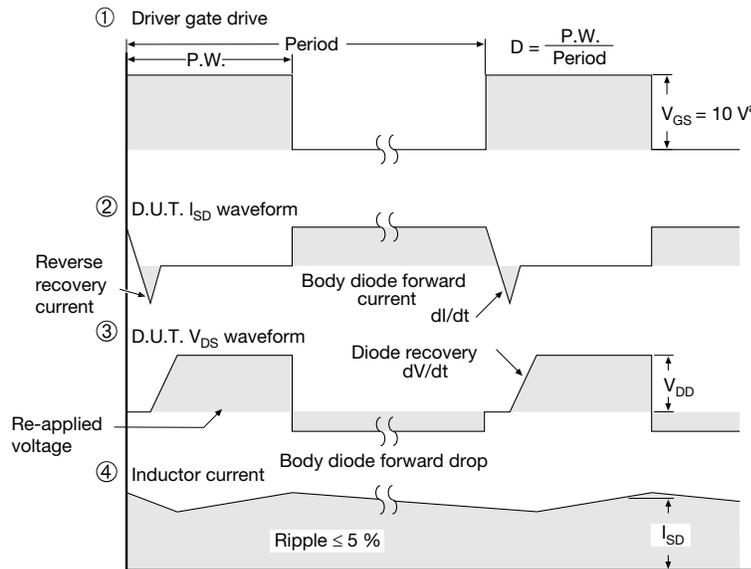
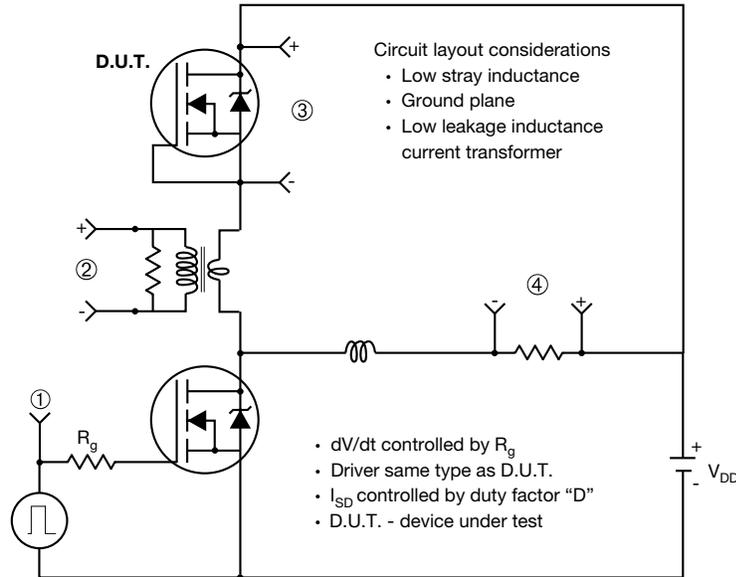


Fig. 13b - Gate Charge Test Circuit

Peak Diode Recovery dV/dt Test Circuit



Note
a. $V_{GS} = 5\text{ V}$ for logic level devices

Fig. 14 - For N-Channel

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